



## DDR4 DIMM

TE Internal #: 2309412-1

Small Outline (SO), 8 mm [.315 in] Stack Height, Right Angle

Module Orientation, 260 Position, DDR4 DIMM, SO DIMM Sockets

[View on TE.com >](#)

Connectors &gt; Socket Connectors &gt; Memory Sockets &gt; SO DIMM Sockets &gt; DDR4 SO DIMM Sockets

DRAM Type: **Small Outline (SO)**Stack Height: **8 mm [.315 in]**Module Orientation: **Right Angle**Number of Positions: **260**Centerline (Pitch): **.5 mm, 5.4 mm, 6.1 mm [.02 in]**[All DDR4 SO DIMM Sockets \(39\)](#)**Features****Product Type Features**

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Cable-to-Board
DRAM Type	Small Outline (SO)

**Configuration Features**

Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	260

**Electrical Characteristics**

DRAM Voltage	1.2 V
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**Signal Characteristics**

SGRAM Voltage	1.2 V
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**Body Features**

Retention Post Location	Both Ends
Retention Post Material	Stainless Steel
Latch Material	High Temperature Thermoplastic



Module Key Type	Offset Right
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Ejector Type	Locking
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Ejector Location	Both Ends
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Connector Profile	High
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#### Contact Features

Contact Current Rating (Max)	.5 A
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Contact Underplating Material	Nickel
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Memory Socket Type	Memory Card
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Contact Base Material	Copper Alloy
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PCB Contact Termination Area Plating Material	Gold Flash
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Contact Mating Area Plating Material	Gold Flash
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#### Termination Features

Insertion Style	Cam-In
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Termination Method to PCB	Surface Mount
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#### Mechanical Attachment

Connector Mounting Type	Board Mount
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PCB Mount Retention Type	Solder Peg
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Mating Alignment Type	Reverse Keying
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PCB Mount Retention	With
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#### Housing Features

Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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Centerline (Pitch)	.5 mm, 5.4 mm, 6.1 mm [.02 in]
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#### Dimensions

Stack Height	8 mm [.315 in]
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Row-to-Row Spacing	8.2 mm [.322 in]
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#### Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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#### Operation/Application

Circuit Application	Power
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#### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	500
Packaging Method	Tape & Reel

### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Out of Scope
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



## Also in the Series | DDR4 DIMM



DIMM Sockets(25)



SO DIMM Sockets(39)

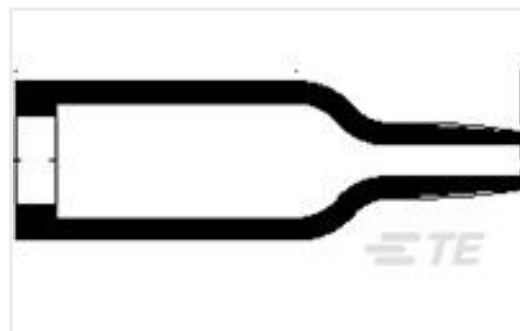
## Customers Also Bought



TE Part #2199119-4  
M.2 0.5PITCH 3.2H KEY E 15U" AU



TE Part #CAT-D33047-SO1339  
DDR4 SO DIMM Sockets



TE Part #CA7241-000  
204W511-25/225-0



TE Part #2007254-1  
SFP+ 1x1 Cage Assembly, Light Pipe



TE Part #2213775-7  
AV16 SPM 0.4VA POWER LED GREEN  
12V



TE Part #2118707-4  
1 PC STD SHIELD, AL-16.50X16.50X3.  
60MM



TE Part #HD34-24-91PN  
REC, 9P, AL, N, 8/12/16, P

## Documents

### Product Drawings

[DDR4 SODIMM 260P 8.0H RVS](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2309412-1\\_1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309412-1\\_1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309412-1\\_1.3d\\_stp.zip](#)



English

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[Product Specifications](#)

[Application Specification](#)

English